

## mAgic DA295A

### Non-Pressure Sinter Paste

mAgic sinter paste DA295A is a lead-free die attach solution with improved workability and performance to meet challenging demands of semiconductor packaging.

#### mAgic DA295A benefits

- Lead-free and zero halogen formulation
- Stable rheology
- Excellent dispensing performance
- Open time up to 120mins
- Consistent adhesion on Au surface
- Low temperature processing (200°C and above)
- Void-free
- No cleaning required

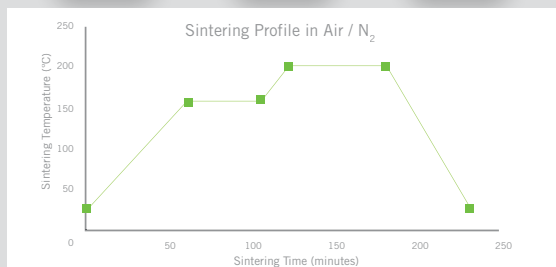


#### Application Information

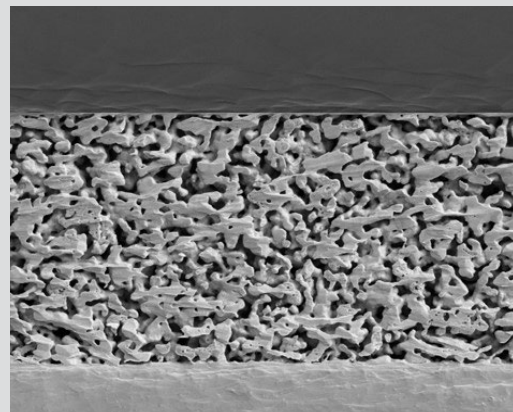
DISPENSE

DIE ATTACH

NON-PRESSURE SINTER



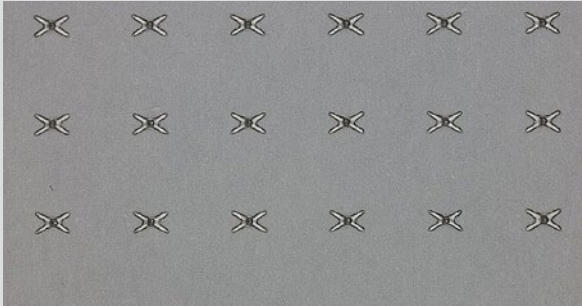
Process parameters can be adjusted depending on application specific requirements



#### Material Comparison

Material Properties	Conductive Adhesive	Solder Paste (PbSn5Ag2.5)	mAgic Sinter Paste DA295A
Process Temperature (°C)	175 ~ 200	360 - 390	≥ 200
Ag Content (%)	75 ~ 85	2.5	100 (after sintering)
Electrical Resistivity (mΩ.cm)	≤ 0.1	0.046	≤ 0.008
Thermal Conductivity (W/m.K)	3 - 10	44	≥ 100
Residue free	Yes	No	Yes
Pb-free	Yes	No	Yes

### Dispensing Performance Over Time




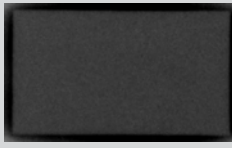




Consistent (no missing or irregular pattern) dispensing up to 12 hours.



No missing or irregular pattern detected.

### Product Properties

Physical Properties	DA295A
Fillers	Silver
Metal content	82 %
Particle size	≤ 25 µm
Sinter temperature	≥ 200 °C
Halogen content	Zero Halogen
Compatible surfaces	Ag / Au
Sinter atmosphere	Air / N <sub>2</sub>
Application/Process	
Dispensing	Yes
Features & Benefits	
Work life	12 hrs
Shelf life	4 mths
Residue cleaning	Not required
Storage condition	2 – 10°C

Open Time	0 hr	1 hr	2 hr
Voids Performance			
High Resolution Magnification			

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